

**(54) PLASTIC MOLDED TYPE INTEGRATED CIRCUIT DEVICE**

(11) 63-244654 (A) (43) 12.10.1988 (19) JP

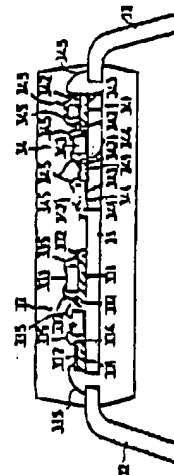
(21) Appl. No. 62-76176 (22) 31.3.1987

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(51) Int. Cl. H01L23/28

**PURPOSE:** To cope with an increase in the number of semiconductor chips to be mounted, by a method wherein two or more insulating substrates are arranged on an island of a lead frame, hybrid units are formed on individual insulating substrates and the units are sealed collectively so that the individual insulating substrates can be miniaturized.

**CONSTITUTION:** A hybrid integrated circuit 23 is composed of insulating substrates 331 and hybrid units. The insulating substrates 331 are fixed to an island 31 by using, e.g., an adhesive; the hybrid units are composed of conductor wiring parts 332 formed on the insulating substrates 331, two or more semiconductor chips 333 and wires 335. Also another hybrid integrated circuit 34 contains the hybrid units which are composed of insulating substrates 341, conductor wiring parts 342, semiconductor chips 343 and wires 345. If the hybrid units which are formed on the separate insulating substrates 331, 341 are plastic-sealed collectively and the number of the insulating substrates to be built in is decided appropriately, it is possible to miniaturize the individual insulating substrates.



25/1/78